

SLHC Phase I & II Upgrades



Roma, March 16th, 2008

G. Darbo - INFN / Genova



Agenda Page:

ATLAS Upgrade Week - Highlights

● AUW – 23-27/2/2009 –

- Indico agenda: <http://indico.cern.ch/conferenceDisplay.py?confId=45460>
- Some statistics: 29 Sessions ~232 Talks ~232 People?

● AUW themes:

- *Moving from R&D based towards a systematic project*
- *Phase II Lol - 2010*
- *Layout Task Force*
- *Joint TDAQ/Systems effort kick-off*
- *IBL TDR - Begin 2010*

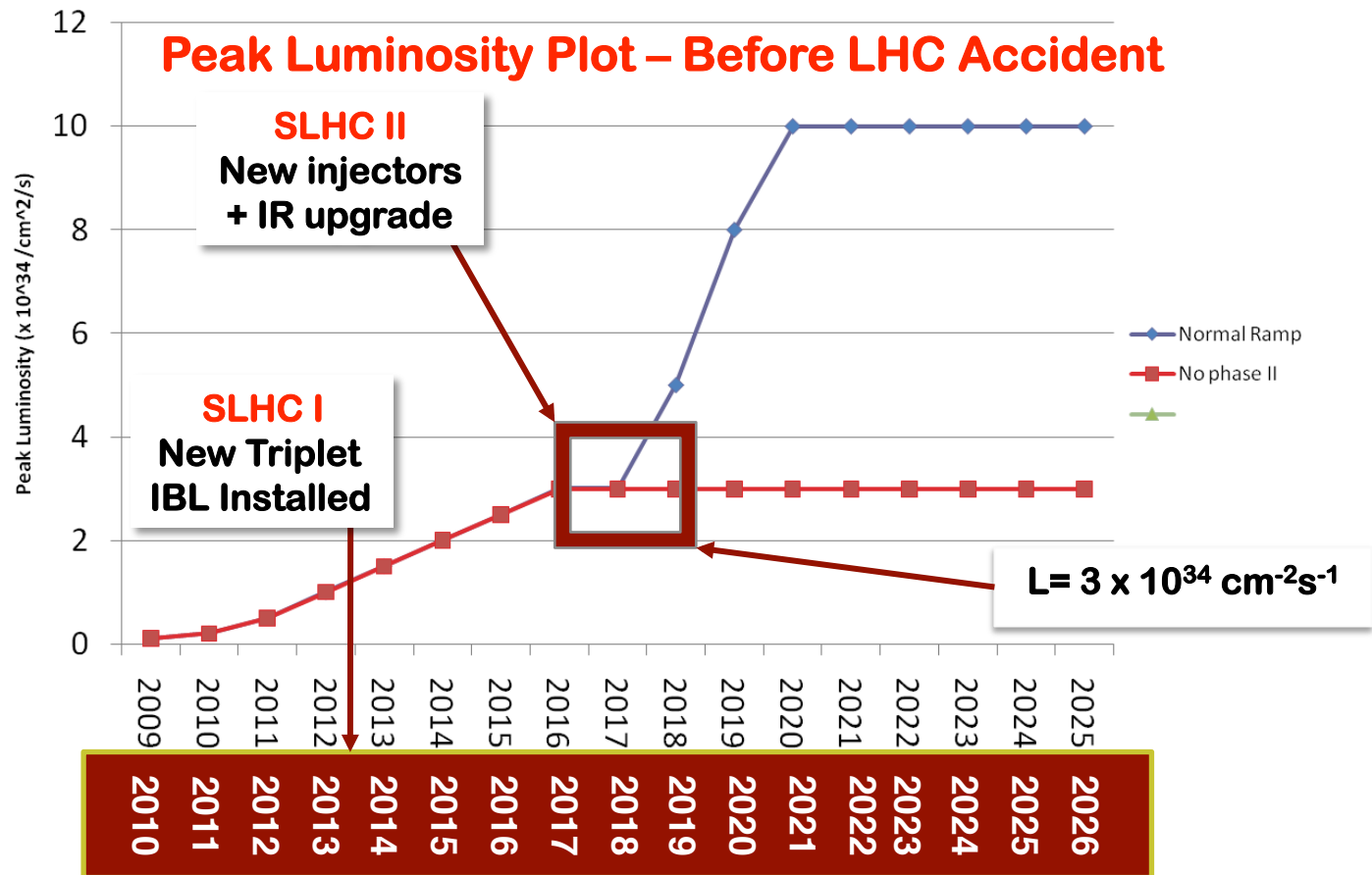
● AUW News – Phase I delayed by one year: 2013→ 2014

- *M. Nessi reported L. Evans words.*

● Next AUW

- *2009 – CERN 26-30/10/2009*
- *2010 – two AUW (proposed end of September in Prague)*

LHC: Luminosity Plot



Shifted by one year

Ref. F. Zimmermann - AUW

SLHC Phase I delayed by one year 2014

Ref.: M. Nessi (AUW) from L. Evans

Luminosity Plot

Ref. R. Garoby – LHCC 1/7/2008 =

<http://indico.cern.ch/conferenceDisplay.py?confId=36149>

SLHC

- November 2008 - Total of 34 proposals or expression-of-interest submitted since 2005. ~210 Institutes participating (multiple times), 7% of INFN
- Two new Eols:
 - TDAQ upgrade (Norman Gee) – see *atlas-tdaq@cern.ch* mail archive (<http://groups.cern.ch/>)
 - LV1 track trigger (Richard Brenner) – see: <https://edms.cern.ch/document/985096>
- R&Ds working groups as backbone of Lol
 - *mapped into Lol sections.*

Inner Tracker R&D

Status – November 2008
Approved by Executive Board
EoI, Proposal presented to USG

Pixel
Strips
Inner Detector

Approved Document	Short name	Title	Principle contact	Institutes
ATL-PA-MN-0007	3D Sensors	Development, Testing and Industrialization of Full-3D Active-Edge and Modified-3D Silicon Radiation Pixel Sensors	Cinzia Da Vià, Sherwood Parker, Giovanni Darbo	CNM Barcellona, Bonn, Freiburg, Genova , Glasgow, Hawaii, LBNL, Manchester, Oslo, SINTEF Oslo, Prague, MBC/Stanford, IRST Trento, Valencia
ATU-RD-MN-0010	Thin Pixels	R&D on thin pixel sensors and a novel interconnection technology for 3D integration of sensors and electronics	H-G. Moser	Bonn, Dortmund, Interon, MPP Munich, Oslo
ATU-RD-MN-0012	Diamond	Diamond Pixel Modules for the High Luminosity ATLAS Inner Detector Upgrade	Marko Mikuž	Bonn, Carleton, CERN, Jožef Stefan Institute, Ohio State, Toronto
ATL-P-MN-0016	Gossip	R&D proposal to develop the gaseous pixel detector Gossip for the ATLAS Inner Tracker at the Super LHC (SLHC)	Harry van der Graaf	NIKHEF, SACLAY, Twente
ATU-RD-MN-0016	Pixel Local Supports	Expression of Interest Research and Development Local Supports for Pixel Detector Upgrades	M. Gilchriese	CPPM, Genova , Milano , LAPP, LPNHE, LBNL, Ohio, SLAC, Toronto, Washington, Wuppertal
ATU-RD-MN-0019	Planar Pixel	R&D on Planar Pixel Sensor Technology for the ATLAS Inner Detector Upgrade	D. Muensterman	Prague, LAL Orsay, Bonn, HU Berlin, TU Dortmund, MPP Munich, MPI Munich, Udine , Liverpool, UNM Albuquerque, UCSC Santa Cruz.
ATL-PA-MN-0002	ABC-Next	Proposal to develop ABC-Next, a readout ASIC for the S-ATLAS Silicon Tracker Module Design	Francis Anghinolfi, Wladek Dabrowski	Cambridgs, CERN, Geneva, Glasgow, Krakow, KEK, Liverpool, London, Ljubljana, Santa Cruz, Valencia
ATL-PA-MN-0004	Staves	Development and Integration of Modular Assemblies with Reduced Services for the ATLAS Silicon Strip Tracking Layers	C. Haber, M. Gilchriese	BNL, Hampton, Santa Cruz LBNL, New York, Milano
ATL-PA-MN-0005	n-in-p sensors	Development of non-inverting Silicon strip detectors for the ATLAS ID upgrade	Hartmut Sadrozinski	KEK, Tsukuba, Liverpool, Glasgow, Lancaster, Sheffield, Cambridge, London, Freiburg, MPI, Ljubljana, Prague, Barcelona, Valencia, Santa Cruz, BNL
ATL-PA-MN-0006	SiGe chips	Evaluation of Silicon-Germanium (SiGe) Bipolar Technologies for Use in an Upgraded ATLAS Detector	Alex Grillo, S. Rescia	IN2P3, CNM Barcelona, BNL, UC Santa Cruz, U of Pennsylvania
ATU-RD-MN-0007	Modules	R&D towards the Module and Service Structure design for the ATLAS Inner Tracker at the Super LHC (SLHC)	Yoshinobu Unno	KEK, Geneva, Freiburg, Melbourne, Valencia, Tsukuba
ATU-RD-MN-0009	SoS	Expression of Interest: Evaluations on the Silicon on Sapphire 0.25 micron technology for ASIC developments in the ATLAS electronics readout upgrade	Ping Gui, Jingbo Ye	SMU Dallas.
ATL-PA-MN-0001	Opto	Radiation Test Programme for the ATLAS Opto-Electronic Readout System for the SLHC for ATLAS upgrades	Cigdem Issever	Taiwan, Ljubljana, Ohio, Oklahoma, Oxford, SMU
ATU-RD-MN-0008	Powering	Research and Development of Power Distribution Schemes for the ATLAS Silicon Tracker Upgrade	Marc Weber	BNL, Bonn, CERN, Krakow, LBNL, RAL, Wuppertal, Yale
ATL-P-MN-0011	Thermal Management	Future ATLAS tracker Thermal Management Research Programme	Georg Viehhauser	BNL, CERN, Genova , Glasgow, KEK, LBNL, Liverpool, Marseille, NIKHEF, Oxford, Prague, QMUL, RAL, Sheffield
ATL-P-MN-0026	ID Alignment	R&D on an Optical Alignment System for the ATLAS Tracker Upgrade at SLHC Based on Straightness Monitoring	J. Dubbert, S. Horvat, O. Kortner, H. Kroha , H.-G. Moser, R. Richter	MPI Munich

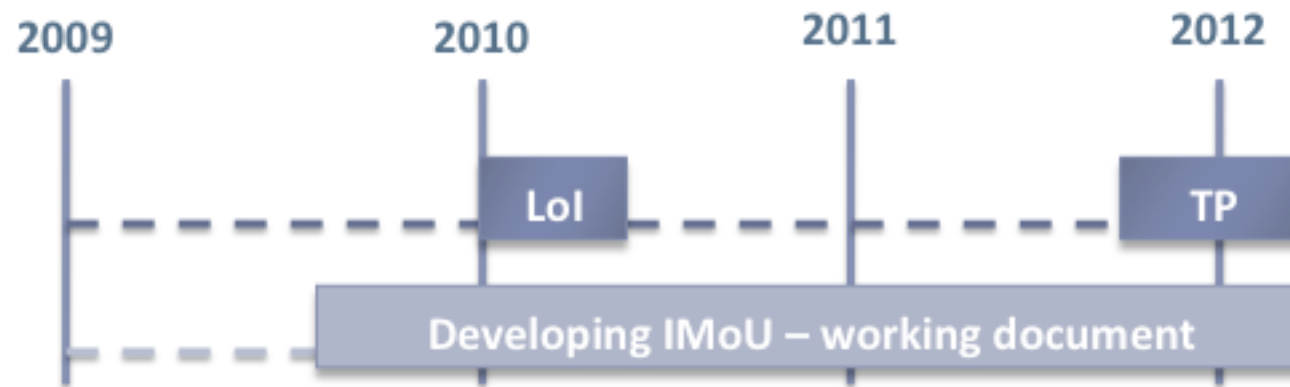
Calorimeter, Muon & Other R&D

Status – November 2008
Approved by Executive Board
EoI, Proposal presented to USC

Calorimeter
Muon
Trigger, Elec, ...

Approved Document	Short name	Title	Principle contact	Institutes
ATL-P-MN-0015	End-Cap LArCAL	A Proposal for R&D to establish the limitations on the operation of the ATLAS End-Cap Calorimeters at high LHC Luminosities	Peter Shacht	Arizona, JINR Dubna, IEP Kosice, Mainz, LPI Moscow, MPI Munich, BINP Novosibirsk, IHEP Protvino, TRIUMF Vancouver, Wuppertal
ATU-RD-MN-0001	Lar FE Electronics	R&D Towards the Replacement of the Liquid Argon Calorimeter Front End Electronics for the sLHC	G. Brooijmans	CERN, LAL-Orsay, Milano , MPI Munich, BNL, Columbia, SMU, New York, Pennsylvania
ATU-RD-MN-0002	LAr Optolink	R and D of a radiation resistant high speed optical link for the ATLAS Liquid Argon Calorimeter readout	Jingbo Ye	
ATU-RD-MN-0003	LAr ROD	Research and Development of Readout Driver (ROD) for the upgrade of the Liquid Argon Calorimeter Front-End Readout	Hucheng Chen	Arizona, BNL, CERN, LAPP, Milano , Stony Brook
ATU-RD-MN-0004	FCAL Cold	Development of new ATLAS Forward Calorimeters for the Upgrade	J.Rutherford	Arizona, Carleton, Toronto.
ATU-RD-MN-0015	Tile Electronics	R&D on Tile Calorimeter Electronics for the sLHC	C. Bohm, L. Price, J. Valls Ferrer	Argonne, Barcelona, Bratislava, CERN, Chicago, Lisbon, Pisa , Prague, AS CR, Stockholm, Valencia.
ATU-RD-MN-0011	Micromegas	R&D project project on micropattern muon chambers for SLHC	V. Polychronakos, J. Wotschack	Arizona, Athens (U, NTU, Demokritos), Brookhaven, CERN, Harvard, Istanbul (Bogaziçi, Doğuş), Naples , Seattle, USTC Hefei, South Carolina, St. Petersburg, Shandong, Thessaloniki
ATL-P-MN-0014	Segmented Straw	R&D of segmented straw tracker detector for the ATLAS Inner Detector Upgrade	Vladimir Peshekhonov	JINR Dubna, Lebedev Moscow, Moscow, Warsaw
ATL-P-MN-0028	TGC	R&D on Optimizing a detector based on TGC technology to provide tracking and trigger capabilities in the MUON Small-Wheel region at SLHC	G. Mikenberg	BNL, The Weizmann Institute, Tel Aviv, Technion
ATL-P-MN-0029	MDT R/O	Upgrade of the MDT Readout Chain for the SLHC	R. Richter	LMU & MPI Munic
ATL-P-MN-0030	MDT-Gas	R&D for gas mixtures for the MDT detectors of the Muon Spectrometer	P. Branchini	Cosenza, Roma3
ATL-P-MN-0031	MDT-Selective R/O	R&D on Precision Drift-Tube Detectors for Very High Background Rates at SLHC	R. Richter	LMU & MPI Munic
ATL-P-MN-0032	High Rate MDT	R&D on Precision Drift-Tube Detectors for Very High Background Rates at SLHC	R. Richter	LMU & MPI Munic
ATU-RD-MN-0013	Fast Track Trigger	Proposal to prepare a technical design report for FTK, a hardware track finder upgrade to the ATLAS trigger	M. Shochet	Chicago, Frascati , Harvard, Illinois, Pisa, Roma 1.
ATU-RD-MN-0014	LVL1-Calo	ATLAS Level-1 Calorimeter Trigger Upgrade	N. Gee	Birmingham, Heidelberg, Mainz, London, Stockholm, RAL, Michigan, ANL
ATU-RD-MN-0018	Versatile Link	The Versatile Link Common Project	Francois Vasey	CERN, Strasbourg, Oxford, SMU Dallas.
ATL-PA-MN-0003	Radiation BG	Radiation background benchmarking at the LHC and simulations for an ATLAS upgrade at the SLHC	Ian Dawson	Sheffield, Arizona, Ljubljana
ATU-RD-MN-0020	Forward Protons	ATLAS FP: A project to install forward proton detectors at 220 m and 420 m upstream and downstream of the ATLAS detector	A. Brandt	

Lol – Time Line



Immediate Needs:

- Propose **Lol outline** – going through today to get first feedback
- Set up an editorial board - **2 main editors**
- Review working groups, overall (sub-)systems contacts – appoint chapter editors
- Include the current **R&D projects in working groups** as appropriate
- Spot critical issues

Ref. M. Capeans – Upgrade PO & SG -3/3/2009

Lol Structure

Intro & Overview

Sub-systems

Performance

Installation

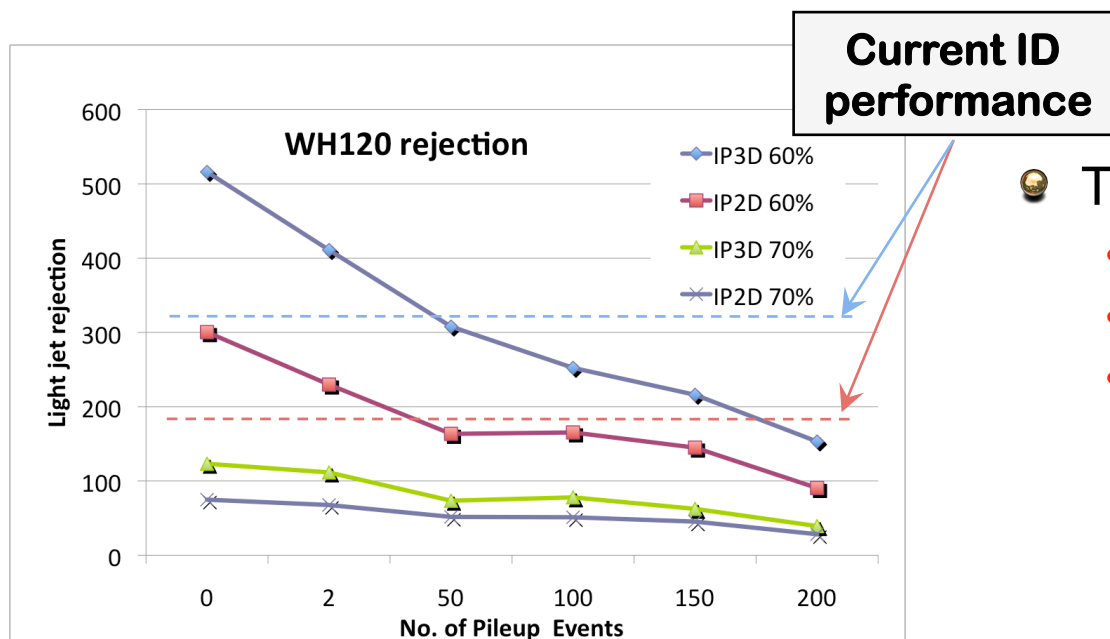
Responsibilities

1) LoI Structure	2) Existing Working Groups or Defined Overall Contacts	3) Links in USG	4) Existing R&D Projects	5) Technology-driven R&D
Members of the ATLAS Upgrade Collaboration			<i>In green, means APPROVED</i>	SiGe chips (ID, LAr) A.Grillo, S.Rescia SoS J.Ye Opto link C.Issever Versatile Link F.Vasey
Introduction & Overview	Physics Goals Current Detector Performances and Limitations Upgrade Motivation Experimental conditions (rad levels, rates, pile-up, etc) Detector Upgrades Unaffected systems Possible upgrades scenarios			
Radiation Environment	Simulations and comparison with exp. data Doses, background studies Re-evaluation rad damage for different LHC working points	Radiation I.Dawson	Radiation BG I.Dawson	
Inner Tracker	Physics Requirements at SLHC and Current Performances Layout: Physics requirements Trigger potential Mechanics & Services Beam pipe issues PIXEL system Short strip system Long strip system Front-End electronics Assembly, integration (Services)	Layout (to be handled by TASK FORCE) N.Hessey B-layer replacement (for phase I) G.Darbo (understand Pixel PhaseI organization) Silicon sensors N. Unno Module Integration P.Allport Module production & qualification Engineering & Integration A. Catinaccio Thermal Management G.Viehhauser Services N.Massol	ID system A.Seiden, G.Darbo, TRT Rep. 3D Sensors S.Parker, C.Da Via Thin Pixels H.G.Moser Diamond M.Mikkuz Planar pixel D.Muenstermann Pixel Support M.Gilchriese Gossip H.van der Graaf Staves G.Haber, M.Gilchriese ABCNext F.Anglinoff, W.Dabrowski n-in-p sensors H.Sadrozinski Modules N.Unno Powering M.Weber ID alignment H.Kroha	
Calorimeter System	Physics Requirements at SLHC and Current Performances Electronics changes LAR Barrel LAR EC FCAL Tiles	Electronics P.Farhouat	LAr system F.Lanni, C.Zeitnitz Tiles C.Bohm	FCAL cold J.Rutherford Lar FE electronics G.Broojmans Lar Optolink J.Ye Lar ROD H.Chen Tile-electronics C.Bohm
Muon Spectrometer	Physics Requirements at SLHC and Current Performances Muon rates Tracking systems upgrade: Big Wheels Small Wheels Trigger systems upgrade	Electronics P.Farhouat	Muon system T.Kawamoto	Muon Micromegas V.Polychronakos, J.Wotschack MDT readout R.Richter MDT Gas P.Branchini Selective readout R.Richter High rate MDT R.Richter TGC G.Mikenberg
Trigger and DAQ	Physics Requirements at SLHC and Current Performances Changes to lv1 trigger Changes to HLT trigger		TDAQ N.McGee	Fast Track Trigger M.Sochet LVL1-Calo N.Gee Track-Trigger R.Brenner
Computing	Changes in computing infrastructure		None currently	
Detector Performance	Expected Detector Performance for different scenarios Trigger Rates Physics performance	C.Young, A.Rimoldi	To be discussed To be discussed	
Experimental Area, Integration and Installation	Changes of general infrastructure DCS Beam pipe and machine interface Installation scenarios Handling, removal and storage of parts (radiation aspects) Safety aspects	Cooling ID DCS A.Cattai D.Ferrere R.Vuillermet A. Catinaccio Engineering & Integration O.Beltramello	Machine Interface P.Grafstrom	
Cost and Responsibilities	Collaboration & Management Structure R&D Projects Schedules Responsibilities Cost (for different scenarios)	N.Hessey I.Wilmot		

Ref. M. Capeans
Upgrade PO & SG -3/3/2009

Layout Task Force

- 3 ID strawman layouts for SLHC have been studied so far (2006, 2007, 2008)
- Limitations have shown-up at $\ll 400$ pile-up events
- A Lol for SLHC is due early 2010, we therefore must converge on a defensible ID layout by then.



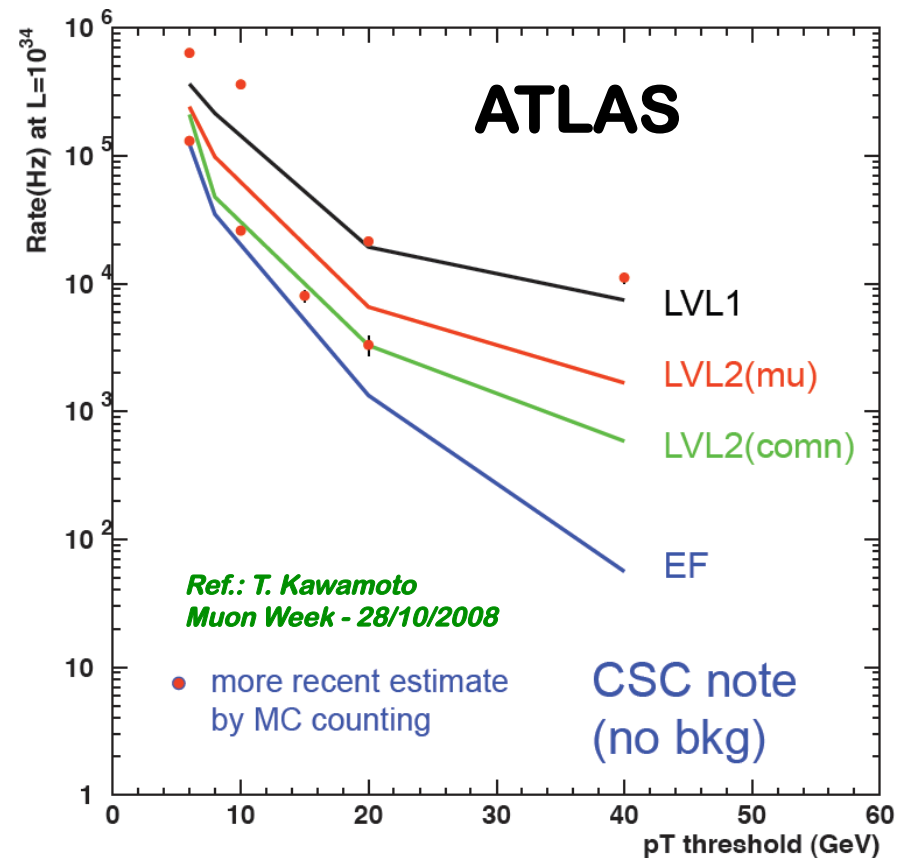
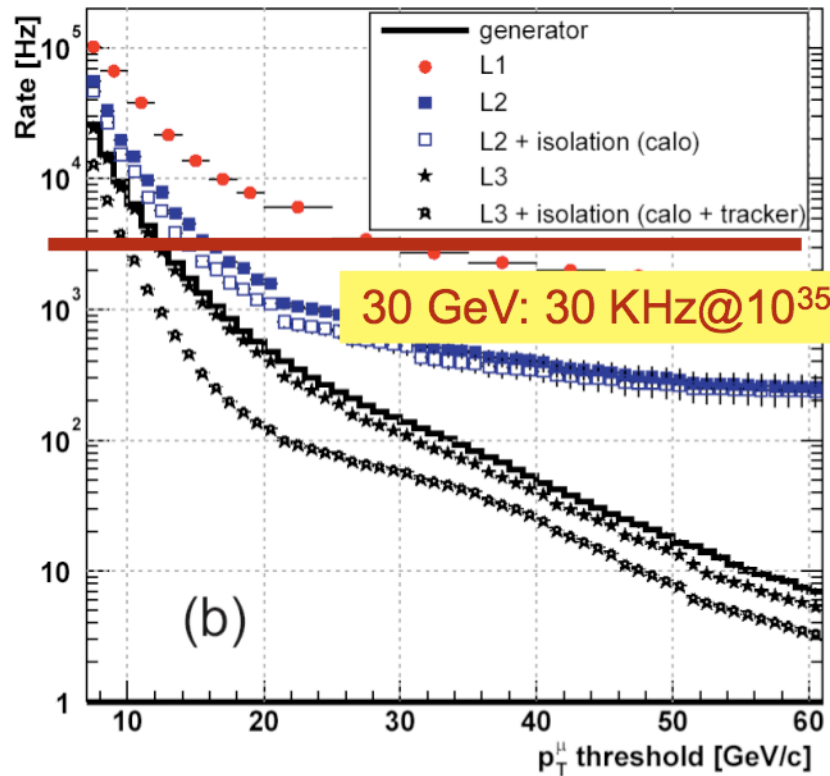
Task Force:

- Chaired by: Leonardo Rossi
- Report in 6 months
- First ideas and strategy at AUW

Ref. L. Rossi - AUW

Single Muon Triggers

From CMS-DAQ TDR



- No control of rate for $p_T > 20$ GeV/c
- Physics rates still OK $p_T > 20$ GeV/C
 - CMS : L3 - ATLAS : EF*
- Use track trigger?
 - CMS going this way, ATLAS is still studying a solution.*

● SLHC Phase I

- *Several detectors have limited event volume; L1A rate at 3×10^{34} will be limited to 50-60kHz at 100% traffic levels*
- *Some detector inefficiencies as latency approaches $2.5 \mu\text{s}$*

● SLHC Phase II

- *Several detectors can use fast clear or trigger directly from level 1.5*
- *For most, $6.4 \mu\text{s}$ latency is fine. Exception is muon $3.2 \mu\text{s}$*
- *Options to improve muon trigger rates by adding chambers*

● Write R&D proposal for TDAQ upgrade work

- *Define document structure, appoint chapter editors, ...*
- *Covering Phase-I and Phase-II, plus evolution*

● Level-1 Trigger

- *Phase I topological upgrade – (Still need to prove that this is useful...)*
- *Phase II – Track Trigger: both simulation and hardware studies underway → progress at the AUW → need lot of efforts for answers to Lol*

- Incontro a Sestri Levante:
 - *Locazione decentrata*
 - *Alitalia e blocco per incidente dell'autostrada la hanno resa più remota*
 - *Ma la tranquillità del luogo ha permesso una maggior concentrazione sui temi in discussione.*
- 50 partecipanti:
 - *ATLAS, CMS, CSN1 (Nando + referee), Umberto e Sergio sono intervenuti in remoto (la GE li ha trattieneuti a Roma).*
- Sito WEB:
 - <http://iacu-2008.ge.infn.it/>

- Incontro ATLAS/CMS per l'Upgrade a SLHC

Organizzatori

- G. Costa
- M. Curatolo
- S. Dalla Torre
- G. Darbo
- M. de Palma
- M. Diemoz
- F. Ferroni
- P. Zotto

Sestri Levante - Participants



See report to CSN1

● Upgrade degli Esperimenti

- *Per entrambi gli esperimenti la sfida sono l'ottenimento di prestazioni "simil LHC":*
 - Prestazioni del tracker interno e L1 trigger sono la difficoltà maggiore.
- *Il management INFN ha preso atto dell'esistenza di una importante comunità Italiana che guarda al futuro di LHC (SLHC)*

● ATLAS e CMS @ Phase I

- *ATLAS: B-Layer – "Impossibile" sostituirlo -> IBL*
- *CMS: Il rivelatore a Pixel ha meno "vincoli" -> varie opzioni possibili*

● R&D per SLHC

- *In futuro gli R&D in cui il CERN si impegnerà dovranno essere finalizzati alle necessità degli esperimenti che per gli upgrade.*
- *Nell'INFN gli R&D devono essere "strategici" per la partecipazione delle comunità negli upgrade degli esperimenti. Partecipazione a SLHC di entrambi ATLAS e CMS, ma concentrazione delle attività per mantenere visibilità.*
- *La CSN1 ha una tasca per il 2009... ai referee il giudizio sulle attività...*

Organization, INFN interests, money.

IBL



- Project Leader (IBL-PL) endorsed by ATLAS CB
 - *Technical Coordinator (IBL-TC): H. Pernegger*
- Organization structure in preparation:
 - *Project is an ATLAS Upgrade for Phase I*
 - *Thinking at working groups (WG), technical board (TB), steering group – covering all project (Pixel CORE and TC)*
 - *Report line to Pixel Institute Board (PIB) and Upgrade Project Office (PO)*
- TDR – Early 2010
 - *2 editors (one senior) with overall knowledge of the Pixel detector and involved/interested in the IBL project.*
 - *Try to reduce options for TDR:*
 - Cooling (CO₂ – C₃F₈): 2 kW CO₂ cooling plant to gain experience set up at CERN
 - Sensors: reduce options, define requirements and specifications.

● FE-I4

- *New front-end chip. 50x250 μ m² pixels, 26.9k pixels, 160 Mb/s R/O.*
- *5 labs: Bonn, CPPM, **Genova**, LBNL, Nikhef*

● Sensors

- *3D & Planar (n-in-n) sensors are the options: 3D more charge after life dose (>3x10¹⁵ n/cm²) but scale production needs demonstration. Planar known technology but high Vbias (>800÷1000V) is a system issue.*
- ***Genova** (with IRST in 3D) & **Udine** (3D & Planar) in ATLAS. IRST-FBK, TN & TS in IGRV (3D sensors)*

● Stave mechanics

- *Low density carbon foam structure with titanium or carbon fiber (CF) pipe option. CF pipe advantages: low X₀, thermal matching with carbon foam support, non corrosion issues.*
- *Good progress in CF pipes: tested at 150 atm, no leakage (<10⁻⁷ atm•cc/s). New technology: need qualification for micro-crack development, develop fittings, find second source for production*
- ***Milano** actively involved in the pipe R&D and in the stave design.*

● Stave Flex Hybrid

- *Genova* interested in the development of the “Stave” Flex Hybrid. Nice complement of the stave design in Milano to which the component is tightly connected.

● Module/Stave Loading & QC

- *Genova* interested in a role (to be better defined) in the module testing/stave loading & qualification process.

● PP2

- *Milano* interested in the PP2 deliverable. They will provide it, if design need minimum changes (no redesign of the board).

● Other deliverables / activities

- Under investigation possible contribution on other parts:
- ROD? Existing ROD could be used with DSP code rewriting and FPGA reprogramming, but new design could bridge to SLHC design & improve architecture (slow VME bus access, more memory). *Bologna* considering ROD deliverable, Italian leading role in Pixel DAQ could play a role.
- Opto-link: opto-chip design if a redesign is needed? *Milano* may contribute.

- Costo e finanziamento del progetto in via di definizione
 - *Il costo del progetto in via di definizione. Presentato all'RRB un piano per 4.4MCH nei MOF-B (2009÷2012) che copre il costo "Pixel CORE". Altri finanziamenti tramite nuovi laboratori e MOF-A (Installazione. Cooling plant, new beam-pipe) coprono il rimanente 50%.*
 - *L'INFN è supposto contribuire in modo diretto per il 25% dei 4.4 MCH dei MOF-B e indiretto tramite I MOF-A.*
- MOF-B del 2009. Sono disponibili 134 k€ (201 kCH) di sj.
 - *Opportuno avere una **definizione del progetto (interim MoU) prima di sbloccare la somma.** Responsabilità italiane e del resto della collaborazione in via di definizione.*

● Genova:

- **80 k€:** recupero assegnazione 2008 andata in residuo (quota FE-I4 + contributo)
- **10 k€:** deposizione bumps (4 wafers sensori) e flip-chip (~40 single chip devices)

● Milano (vedi presentazione Danilo):

- **5 k€:** una mini serie di tubi in CF (prototipi già realizzati) per testarne l'affidabilità sotto i vari aspetti: resistenza alla pressione, resistenza alla radiazione, misure di coefficienti termici, etc
- **10 k€:** prototipo di stave completo da caratterizzare sotto vari aspetti e confrontare con le simulazioni realizzate dall'officina meccanica.
- **20 k€:** per sviluppare i fitting in fibra di carbonio tra lo stave e il circuito di cooling fino a PP1, che funzionino ad alta pressione

● Udine (vedi presentazione Mario Paolo):

- **10 k€:** sviluppo e test sensori
- Missioni: MI 1k€, ME 4mu.

Richieste IBL – Sommario 03/09

- Sommario richieste Pixel IBL and SLHC R&D e IBL prototipaggio / costruzione.

Richieste Pixel R&D SLHC / IBL - Marzo 2009					
Sezione	Capitolo	Descrizione	Rias.08	Tasca SLHC	MOF-B IBL
GE	Cons	deposizione bumps (4 wafers sensori) e flip-chip (~40 single chip devices)		k€ 10.0	
		b-layer replacement: produzione sensori 3D alla FBK (ex IRST), 12 maschere, run di 25 wafers	k€ 20.0		
		b-layer replacement: partecipazione (al 25%) al run del circuito di front-end (FEI4)	k€ 60.0		
MI	Cons	BL-replacement -materiale per realizzazione protostave e misure termiche		k€ 10.0	
		BL-replacement - R&D fitting per alta pressione		k€ 20.0	
		BL-replacement - prototipi per qualificazione stave carbonio omogenei (50*100€each)		k€ 5.0	
		MOF-B IBL (201 kCH) - non richiesti a Marzo			k€ 134.0
PI	Cons	R&D slim edge sensori		k€ 10.0	
UD	Cons	Partecipazione produzione sensori planari (10% totale)		k€ 10.0	
Totale richieste Blayer			k€ 80.0	k€ 65.0	k€ 134.0

Sezione	Capitolo	Descrizione	Richieste	sj
GE	Cons	b-layer replacement: prototipo servizi compatibile con il dispositivo attuale	k€ 8.0	
		b-layer replacement: verifica e manutenzione delle 2 clean rooms	k€ 10.0	
		b-layer replacment: bump di 10 moduli alla AMS-Selex (ex Alenia)	k€ 10.0	
		b-layer replacement: produzione sensori 3D alla FBK (ex IRST), 12 maschere, run di 25 wafers	k€ 27.0	Anticipi GE 80 k€
		b-layer replacement: pertecipazione (al 25%) al run del circuito di front-end (FEI4)	k€ 60.0	
MI	Cons	BL-replacement -materiale per realizzazione protostave e misure termiche	k€ 10.0	
		BL-replacement - R&D fitting per alta pressione	k€ 20.0	
		BL-replacement - prototipi per qualificazione stave carbonio omogenei (50*100€each)	k€ 5.0	
		Consumi per camera pulita	k€ 3.0	
		MOFB Pixel 553 kCHF di cui 261kCHF BL Repl.s.j.		k€ 163.0
UD	Cons	licenza software per laboratorio	k€ 2.0	Sono 134 k€ sj
		calibrazione strumenti per laboratorio	k€ 3.5	
		bombole azoto + consumi lab	k€ 5.0	
		manutenzione deumidificatore camera pulita	k€ 0.5	
		Partecipazione produzione sensori planari (10% totale)	k€ 10.0	
	Inv	PC per laboratorio	k€ 2.0	
		impulsatore AGILENT- generatore di segnale a due canali per studi di charge pumping descritti nel proposal per i sensori planari (B-layer replacement)	k€ 20.0	
Totale richieste Blayer			k€ 196.0	k€ 163.0

Richieste finanziarie. Vedi presentazioni separate.

R&D SLHC

Richieste R&D: LAr (FE Elec)

- Interesse manifestato per sviluppo d'elettronica di front-end per calorimetria (nel 2007 e 2008 CSN1, Sestri Levante):
 - *Vedi presentazione Mauro di oggi.*
- Richieste finanziarie per sviluppo elettronica di front-end per calorimetri (Milano):
 1. *Realizzazione di una piccola facility di test per la caratterizzazione delle diverse tecnologie (Progettazione e realizzazione di PCB, Componentistica varia, Schede di interfaccia/acquisizione/memorizzazione):* **7 k€**
 2. *Test con radiazioni (Protoni al TSL di Uppsala ($\sim 2 \times 10^{14}$ p/cm²), Tempo fascio, 11x800 €/ora + set-up dedicato):* **11 k€**
 3. *Partecipazione ad una nuova sottomissione di un test chip (Insieme con le altre istituzioni, lo schema temporale dipende dai risultati sul primo test chip IBM. Possibile nuova sottomissione fine 2009, inizio 2010):* **15 k€.**

Altre Richieste: ...

- Ricevuto solo possibile richiesta di 2 k€ per micromega.
- Altro?
 - *discussione*

Richieste SLHC – 09/08 e 03/09

Richieste Settembre 2008

Sezione	Capitolo	Descrizione	Richieste	sj
LNF	Cons	3 evaluation boards Xilinx (6KEuro), tranceiver ottici e componentistica elettronica varia (2KEuro) per R&D di FastTrack (FTK)	k€ 8.0	
	Inv	Modulo per pattern generator per R&D di FastTrack(FTK)	k€ 16.0	
MI	Cons	SI-Ge-prototipi 24ke - irraggiamento 16ke	k€ 40.0	
NA	Cons	SLHC: prototipi rivelatori	k€ 4.0	
		SLHC: gas (3k€) e sonde gas infiammabile (2k€) per la stazione di test di Napoli	k€ 5.0	
		SLHC: elettronica di front end per i prototipi	k€ 3.0	
	Inv	SLHC: TDC VME	k€ 5.0	
		SLHC: HV power supply (sensib.1nA)	k€ 3.0	
PI	Cons	Sviluppi elettronica FE (SLHC)	k€ 4.0	
		attrezzature banco optoelettronico: test fibre e PMT (SLHC). Posizionatori, diaframmi, polarimetri, fotodiodi calibrati (QE)	k€ 6.0	
	Inv	Alimentatori HV (CAEN 4ch HV NIM Module -N472)	k€ 12.0	
RM2	Cons	Costruzione prototipi RPC di piccole dimensioni con elettronica di FE	k€ 5.0	
		Test alla GIF (gas e affitto pool)	k€ 5.0	
Totale richieste SLHC			k€ 116.0	k€ -

Richieste Marzo 2009 (Sblocchi)

Sezione	Capitolo	Descrizione	Tasca SLHC
MI	Cons	Test setup (boards, schede acquisizione)	k€ 7.0
		Irraggiamenti	k€ 11.0
		Quota engineering run (fine 2009, inizio 2010)	k€ 15.0
NA	Cons	Micromega	k€ 2.0
Totale richieste SLHC			k€ 35.0